

**RSR010N10** 

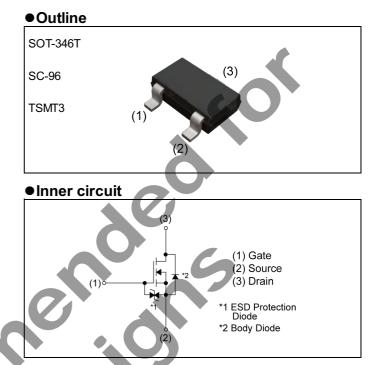
# Nch 100V 1A Small Signal MOSFET

Datasheet

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	520mΩ
I <sub>D</sub>	±1A
P <sub>D</sub>	1.0W

# Features

- 1) Low on resistance
- 2) Built-in G-S Protection Diode
- 3) Small Surface Mount Package (TSMT3)
- 4) Pb-free lead plating ; RoHS compliant



# Packaging specifications

	- 1 0.0110	ging opeenieutiene	
	0	Packing	Embossed Tape
		Reel size (mm)	180
• Application	Туре	Tape width (mm)	8
DC/DC converters		Basic ordering unit (pcs)	3000
		Taping code	TL
		Marking	ZJ

# • Absolute maximum ratings (T<sub>a</sub> = 25°C , unless otherwise specified)

Paramèter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	100	V
Continuous drain current	I <sub>D</sub>	±1	А
Pulsed drain current	I <sub>DP</sub> *1	±4	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *2	1.0	А
Avalanche energy, single pulse	E <sub>AS</sub> *2	0.7	mJ
Dower discinction	P <sub>D</sub> *3	1.0	W
Power dissipation	P <sub>D</sub> *4	0.7	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# •Thermal resistance

			O: make al	Values			
Paramete	er		Symbol	Min.	Тур.	Max.	Unit
	a hia at		$R_{thJA}^{*3}$	-	-	125	°C/W
hermal resistance, junction - ambient			R <sub>thJA</sub> *4	-	-	178	°C/W
●Electrical characteristics (T <sub>a</sub> = 25°C)					G	0	
Parameter	Symbol	Cor	nditions		Values		Unit
Faldmeter	Symbol	CO		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I	<sub>D</sub> = 1mA	100	-	-	V
Breakdown voltage	$\Delta V_{(BR)DSS}$	I <sub>D</sub> = 1mA				mV/°C	
temperature coefficient	$\Delta T_j$	referenced	-	116.9	-	mv/ C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100\	/, V <sub>GS</sub> = 0V		-	1	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20$	/, V <sub>DS</sub> = 0V	5	-	±10	μA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V,	I <sub>D</sub> = 1mA	1.0	-	2.5	V
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = 1mA	0		26		mV/°C
temperature coefficient	ΔTj	referenced	to 25°C	-	-3.6	-	mv/ C
		V <sub>GS</sub> = 10V,	I <sub>D</sub> = 1A	-	370	520	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 4.5V	, I <sub>D</sub> = 1A	-	400	560	mΩ
		V <sub>GS</sub> = 4.0V	, I <sub>D</sub> = 1A	-	410	580	
Gate resistance	R <sub>G</sub>	f = 1MHz, o	pen drain	-	10	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 10V,	I <sub>D</sub> = 1A	1.0	3.1	-	S

\*1 Pw  $\leq 10 \mu s$ , Duty cycle  $\leq 1\%$ 

\*2 L  $\simeq$  1.0mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>j</sub> = 25°C Fig.3-1,3-2

\*3 Mounted on a ceramic board (30×30×0.8mm)

\*4 Mounted on a FR4 (25×25×0.8mm)

\*5 Pulsed





# •Electrical characteristics (T<sub>a</sub> = 25°C)

	Symbol Conditions		Values					
Parameter			Min. Typ.		Max.	- Unit		
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	140	-			
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	20	-	pF		
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	12	-			
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 50 \text{V}, \text{V}_{GS} = 10 \text{V}$	-	6	-			
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 0.5A	-	9	-	20		
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 100Ω	0	22	-	ns		
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	15	-			
• Gate charge characteristics ( $T_a = 25^{\circ}C$ )								
				Values				

# • Gate charge characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Values		Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q <sub>g</sub> *5	V <sub>DD</sub> ≃ 50V,	-	3.5	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 1A,	-	0.9	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 5V	-	0.8	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Conditions	Values			Unit
Palameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>s</sub>	T <sub>a</sub> = 25°C	-	-	0.8	А
Pulse forward current	I <sub>SP</sub> *1	$T_a = 25 C$	-	-	4	А
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A	-	-	1.2	V



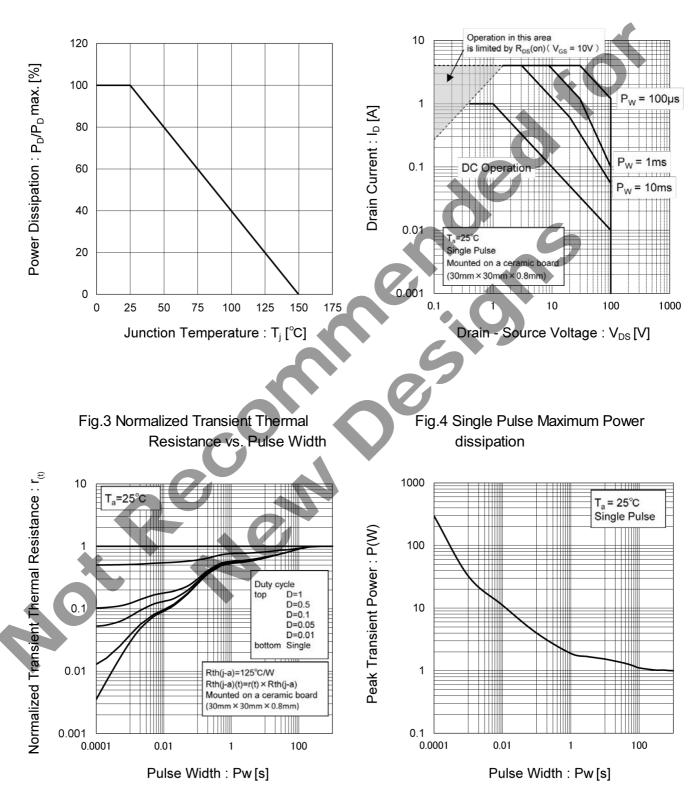


Fig.1 Power Dissipation Derating Curve

# Fig.2 Maximum Safe Operating Area



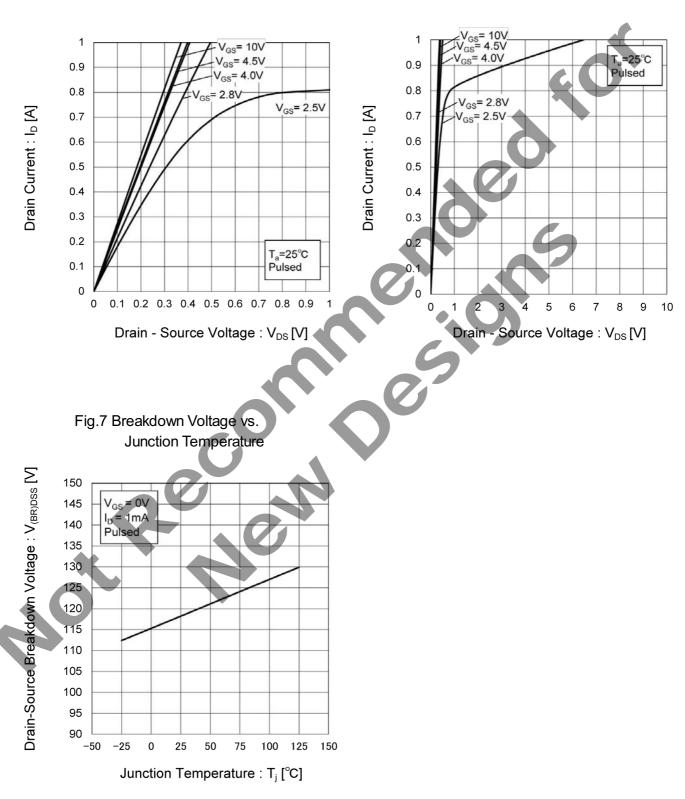
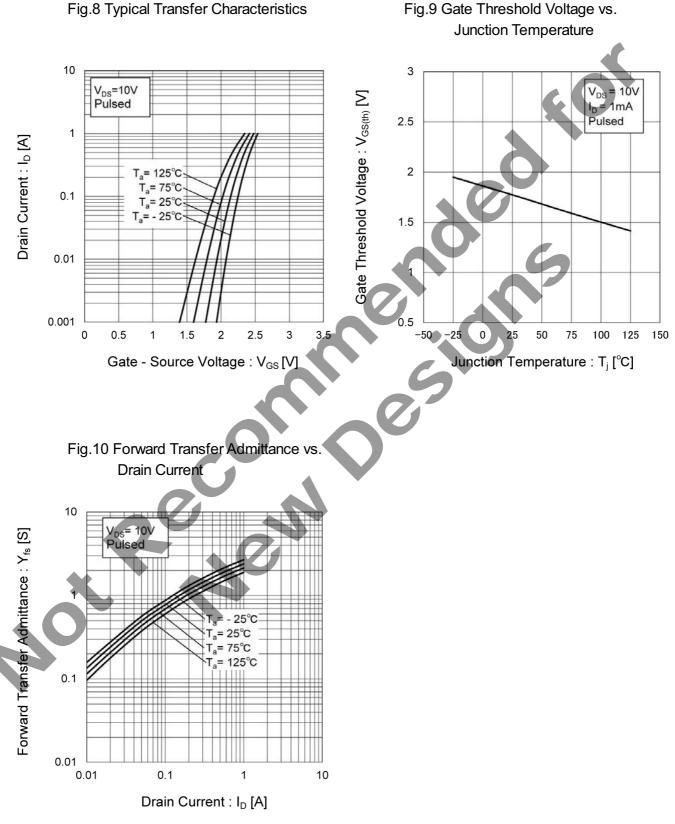


Fig.5 Typical Output Characteristics(I)

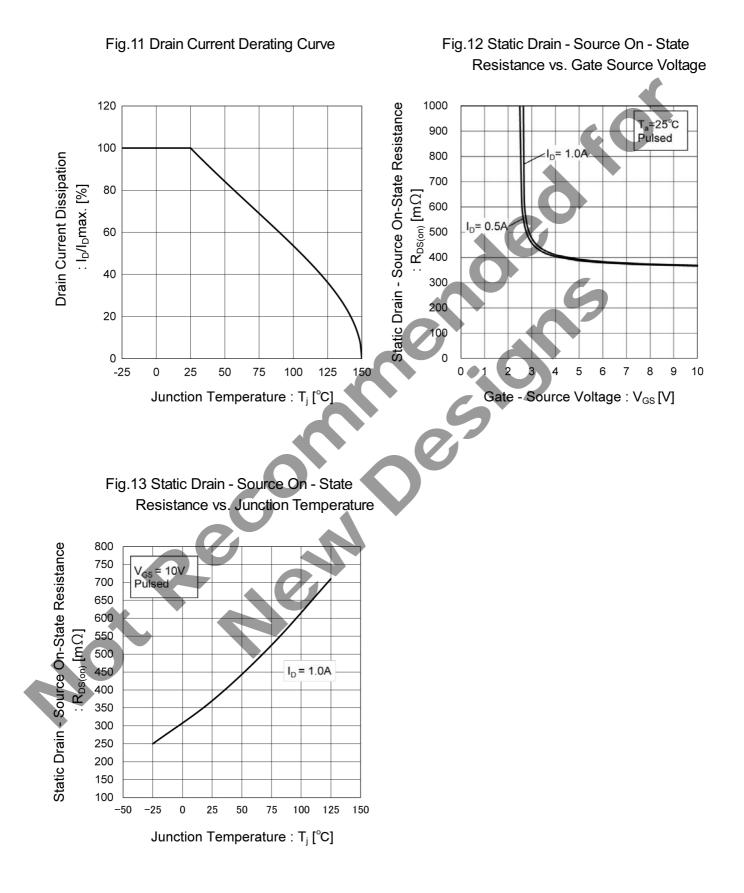
# Fig.6 Typical Output Characteristics(II)



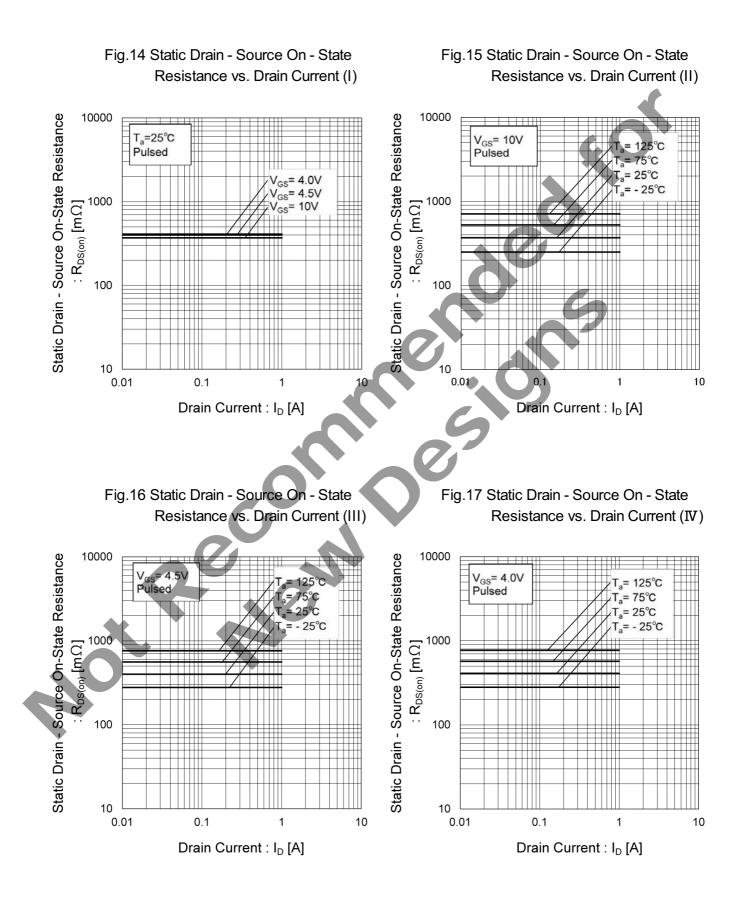




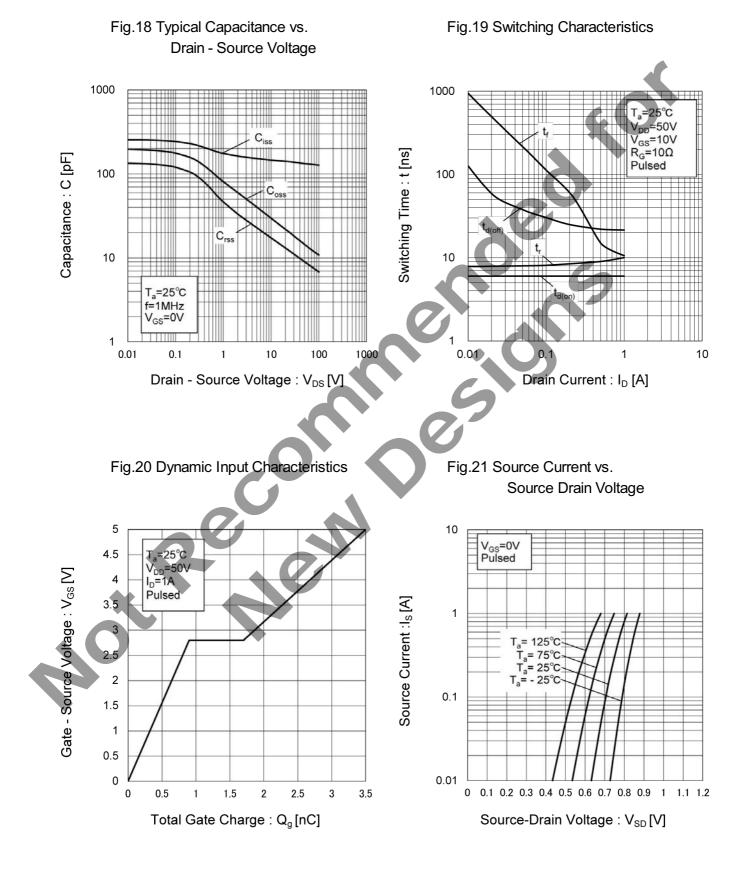








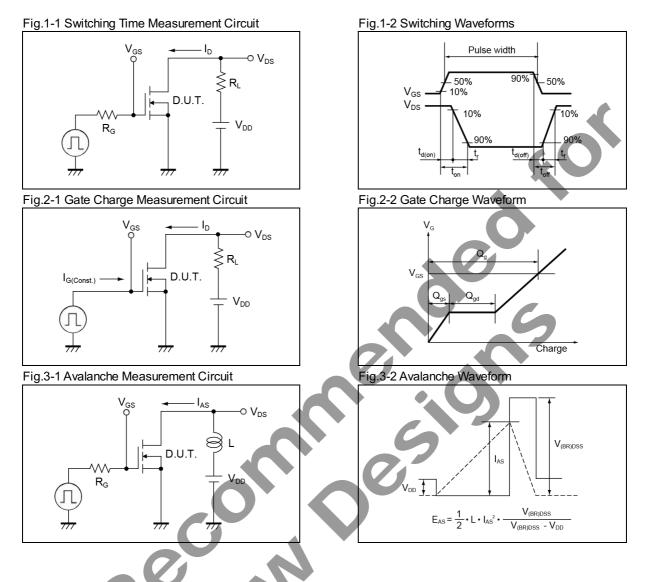




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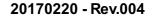


## Measurement circuits



#### Notice

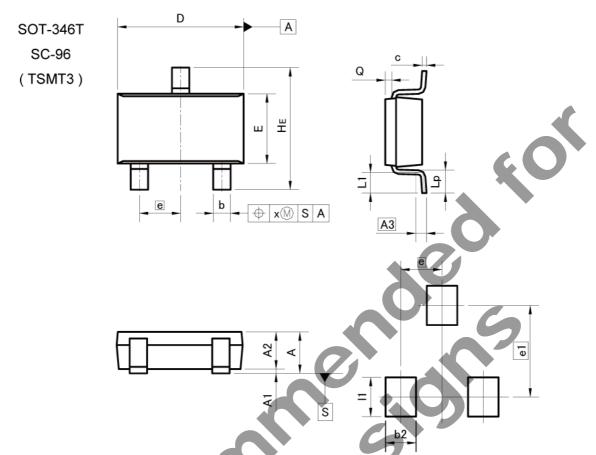
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.





# **RSR010N10**

# Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
A		1.00	—	0.039			
A1	0.00	0.10	0.000	0.004			
A2	0.75	0.95	0.030	0.037			
A3	0.	0.010		0,25 0.01		010	
b	0.35	0.50	0.014	0.020			
c	0.10	0.26	0.004	0.010			
D	2.80	3.00	0.110	0.118			
E	1.50	1.80	0.059	0.071			
е	0.95		0.037				
HE	2.60	3.00	0.102	0.118			
L1	0.30	0.60	0.012	0.024			
Lp	0.40	0.70	0.016	0.028			
Q	0.05	0.25	0.002	0.010			
x	7.53	0.20	<del></del> 8	0.008			

DIM	MILIME	TERS	INCHES		
	MIN	MAX	MIN	MAX	
b2		0.70	57.0	0.028	
e1	2.10		0.0	083	
11	<b>7</b> %	0.90	<u></u>	0.035	

Dimension in mm/inches





# Notice

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(Note1) Medical E	quipment Classifi	cation of the Spec	ific Applications
JAPAN	USA	EU	CHINA

JAFAN	034	EU	GLIINA	
CLASSⅢ	CLASSII	CLASS II b	CLASSI	
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSI	

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

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